

**Material:**

Housing:Hi-Temp Plastic,UL 94 V-0.Rated.

Contact:Copper Alloy.

Shell:Copper Alloy.

**Plating:**

Contact Area:Gold flash.

Solder area:80u" Min,Matte tin alloy plated.

Under plate:30u" min,Nickel.

Shell:30u" Min,Nickel plated overall

Solder area:Gole flash.

**Electrical:**

Current Rating:0.5A.

Withstanding Voltage:AC500V r.m.s.

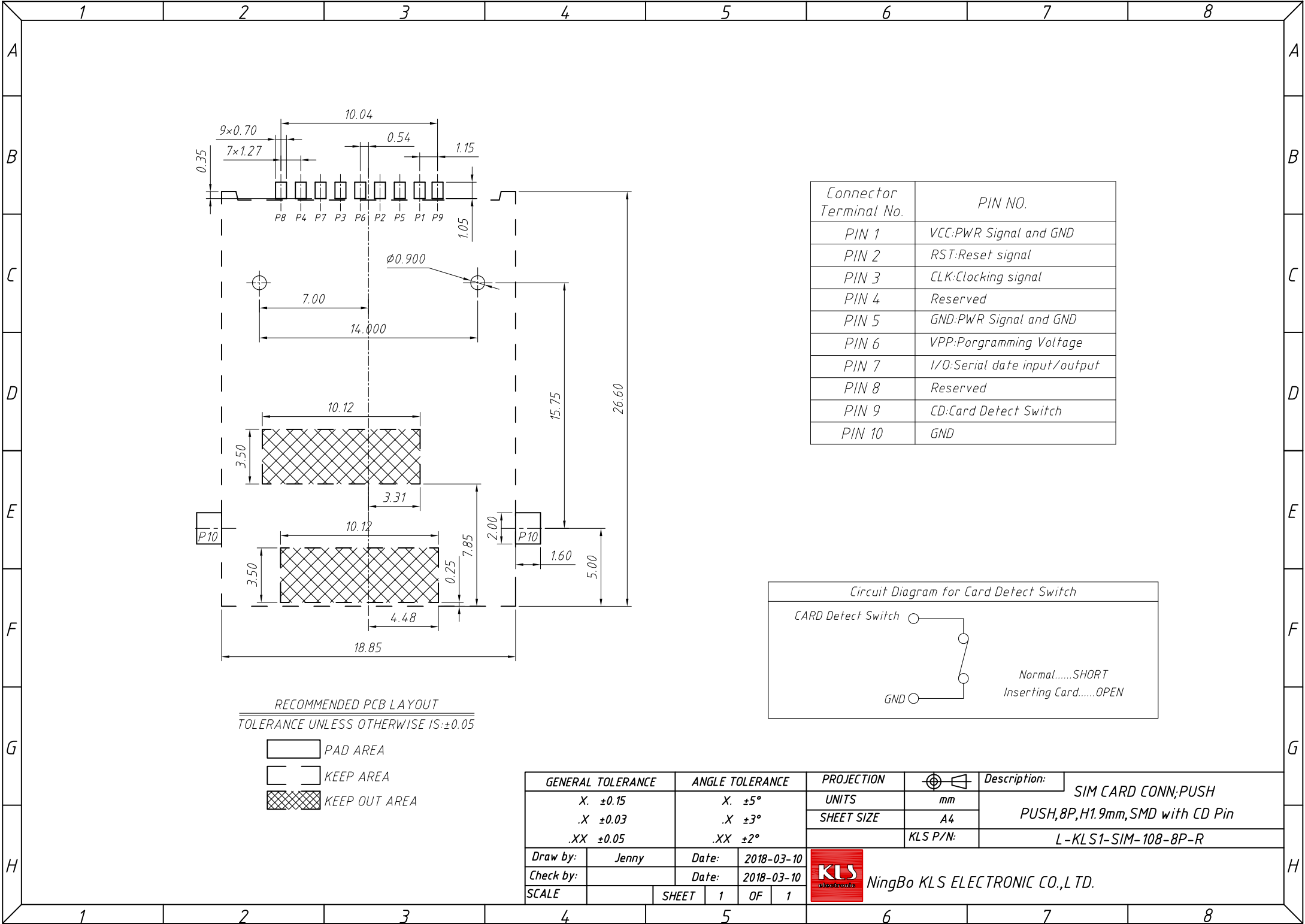
Insulation Resistance:1000M $\Omega$ Min,At DC 500V

Contact Resistance:100m $\Omega$  Max.

Mating Cycles:3000 Insertions.

Operating Temperature:-40°C TO +85°C

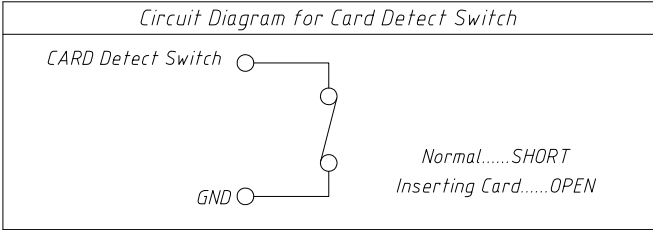
GENERAL TOLERANCE		ANGLE TOLERANCE		PROJECTION	Description:
X. $\pm 0.15$		X. $\pm 5^\circ$		UNITS	SIM CARD CONN;PUSH PUSH,8P,H1.9mm,SMD with CD Pin L-KLS1-SIM-108-8P-R
.X $\pm 0.03$		.X $\pm 3^\circ$		SHEET SIZE	
.XX $\pm 0.05$		.XX $\pm 2^\circ$		KLS P/N:	
Draw by:	Jenny	Date:	2018-03-10	 NingBo KLS ELECTRONIC CO.,L TD.	
Check by:		Date:	2018-03-10		
SCALE		SHEET	1 OF 1		



RECOMMENDED PCB LAYOUT  
TOLERANCE UNLESS OTHERWISE IS:±0.05

- PAD AREA
- KEEP AREA
- KEEP OUT AREA

Connector Terminal No.	PIN NO.
PIN 1	VCC:PWR Signal and GND
PIN 2	RST:Reset signal
PIN 3	CLK:Clocking signal
PIN 4	Reserved
PIN 5	GND:PWR Signal and GND
PIN 6	VPP:Porgramming Voltage
PIN 7	I/O:Serial date input/output
PIN 8	Reserved
PIN 9	CD:Card Detect Switch
PIN 10	GND



GENERAL TOLERANCE		ANGLE TOLERANCE		PROJECTION		Description:	
X	±0.15	X	±5°	UNITS	mm	SIM CARD CONN;PUSH PUSH,8P,H1.9mm,SMD with CD Pin L-KLS1-SIM-108-8P-R	
.X	±0.03	.X	±3°	SHEET SIZE	A4		
.XX	±0.05	.XX	±2°	KLS P/N:			

Draw by: Jenny Date: 2018-03-10  
 Check by: Date: 2018-03-10  
 SCALE SHEET 1 OF 1

**KLS** NingBo KLS ELECTRONIC CO.,L TD.